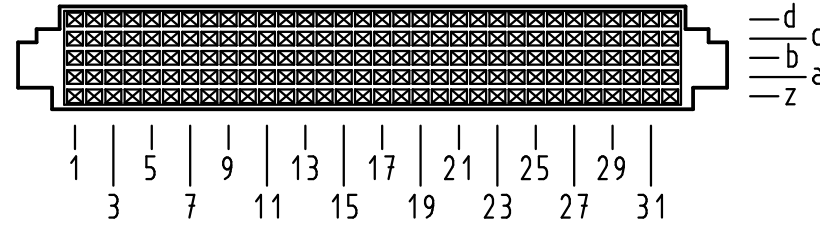


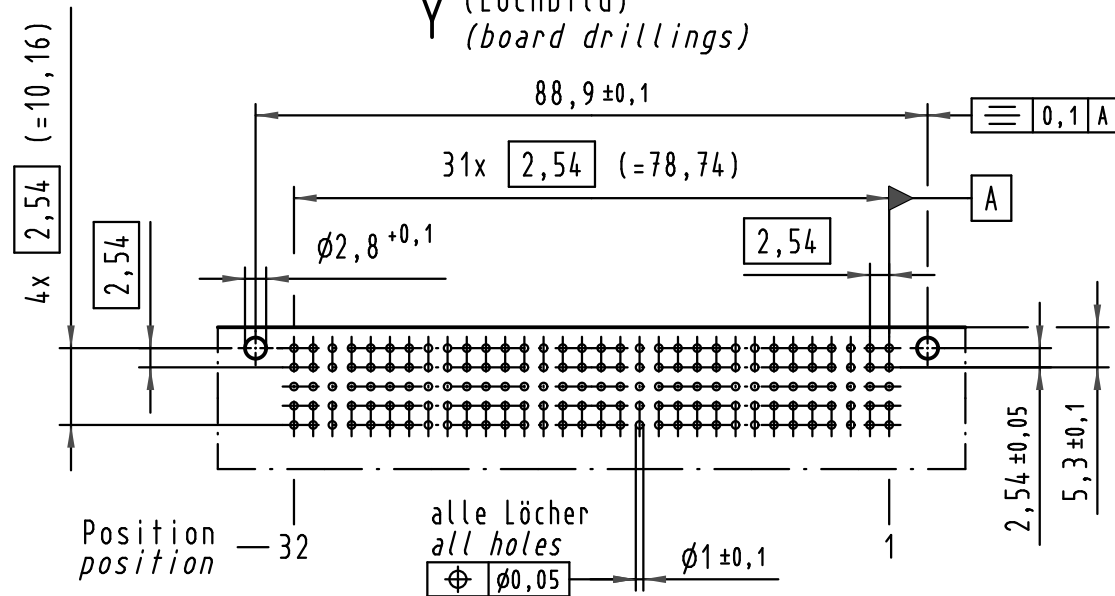
X
Kontaktanordnung
contact arrangement



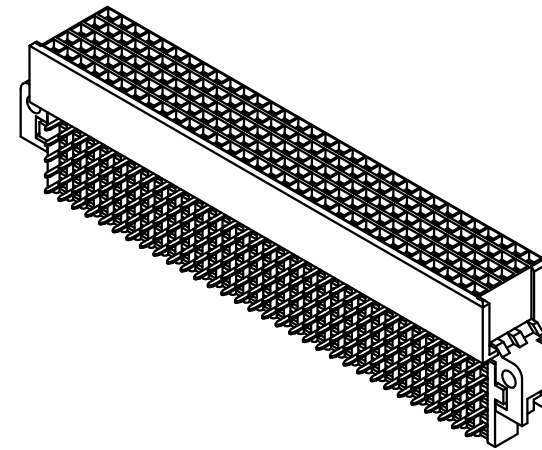
160 Signal Kontakte
160 signal contacts

- ☒ = Kontaktposition belegt
= position with contact
- = Kontaktposition nicht belegt
= position without contact

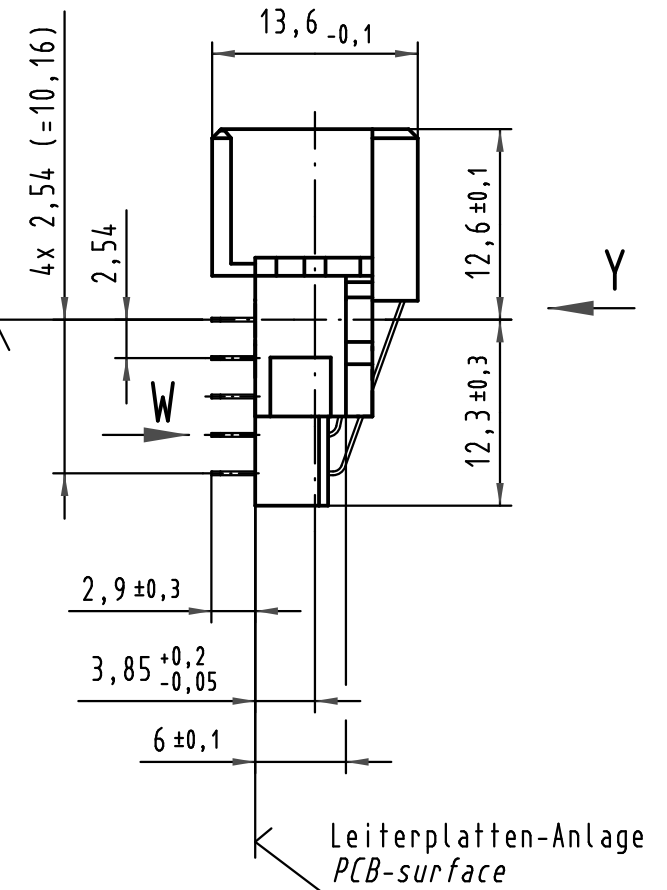
Y (Lochbild)
(board drillings)



Mitte Befestigungsbohrung
centre line of mounting hole



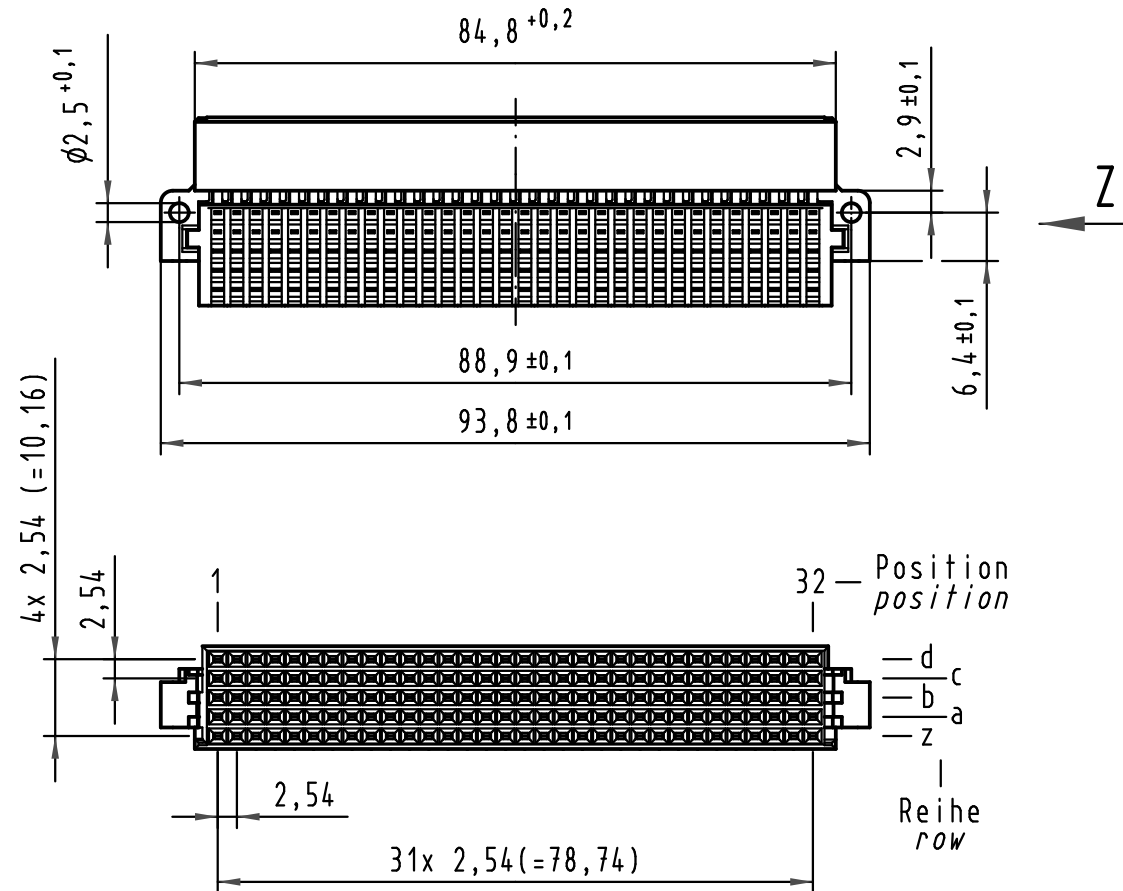
Z
2:1



Leiterplatten-Anlage
PCB-surface

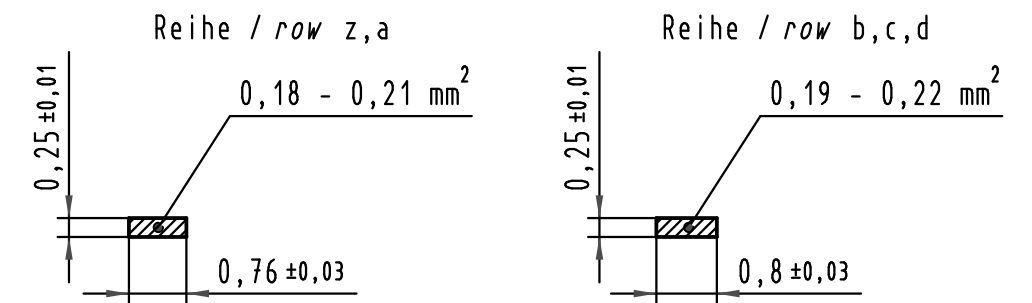
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X



Z

W
10:1
Querschnitt der Lötanschlüsse:
cross-section of solder terminations:



02 04 160 1101	1	Au über/over Ni
Bestell-Nr. part-No.	Anforderungsstufe nach IEC performance level acc. to IEC	Kontaktoberfläche contact plating

All Dimensions in mm Original Size DIN A 3			Techn. Character.			Nicht tolerierte Maß/Free size tolerances ergänzend/complementary IEC 61076-4-113		
35956	03.12.09	Hage.		Dat.	Name	Maßstab/Scale 1:1 2:1 10:1	har-bus 64 Transition Connector	
32569	11.03.05	Hil	Detail.	17.03.97	HL.		Einlöt 160 pol.	
31166	02.08.02	HL.	Insp.	17.03.97	Pa.		solder 160 pol.	
29422	16.03.01	Rie.	Stand.					
21917	25.09.98	HL.	HARTING Electronics GmbH & Co. KG				TB 02 04 160 x101	
20654			D-32339 ESPELKAMP				Blatt/page	
Mod.	Dat.	Name				Sub.		